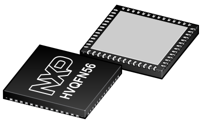


SOT684-25(DD)

HVQFN56, thermal enhanced very thin quad flat package; no leads; dimple wettable flank; 56 terminals; 0.5 mm pitch, 8 mm x 8 mm x 0.85 mm body

3 September 2018 **Package information**

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN56
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Mounting method type	S (surface mount)
Issue date	01-08-2018
Manufacturer package code	98ASA01263D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	8	-	mm
package width	-	8	-	mm
seated height	-	0.85	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	56	-	

2 Package outline

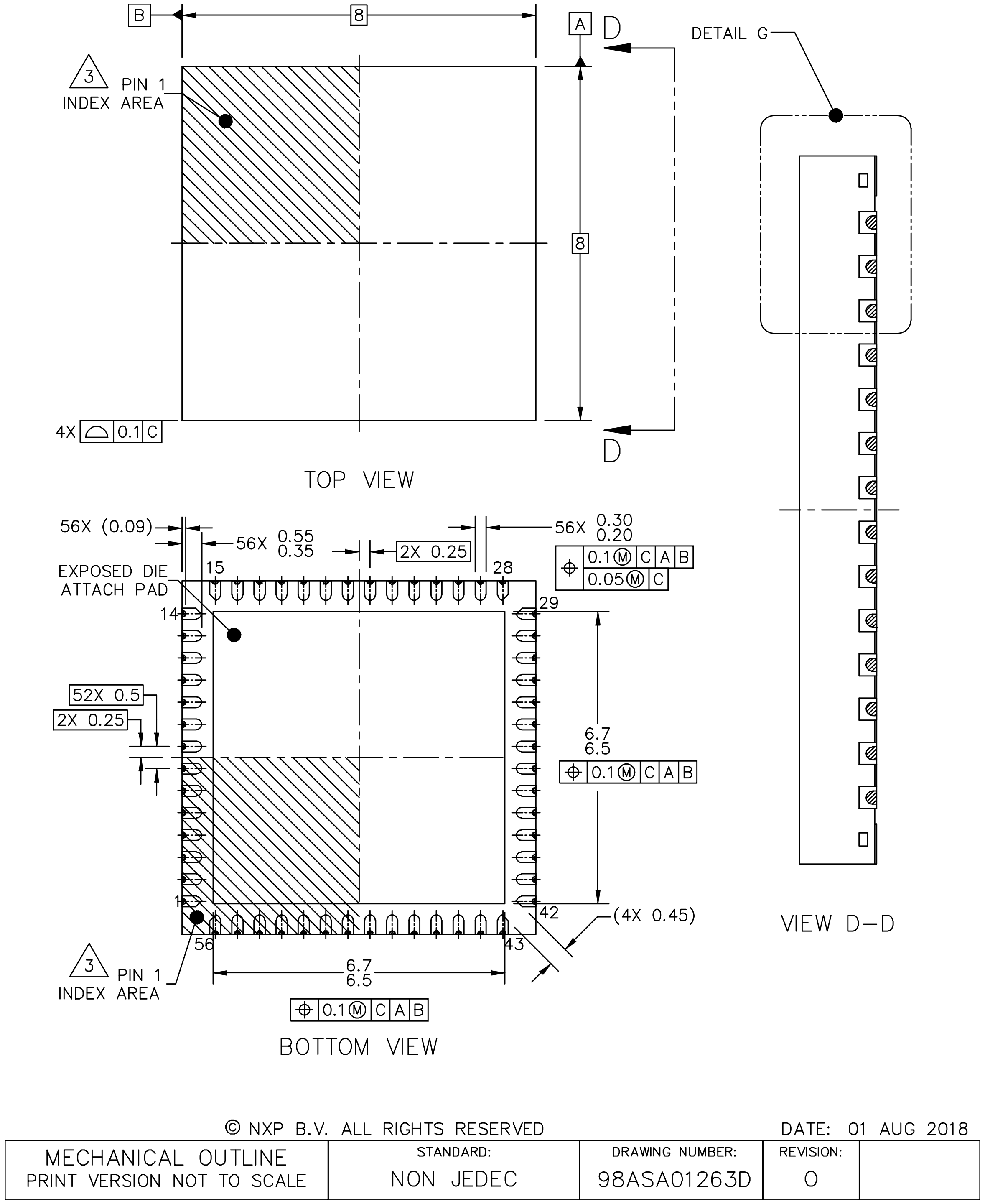


Figure 1. Package outline HVQFN56 (SOT684-25(DD))

HVQFN56, thermal enhanced very thin quad flat package; no leads; dimple wettable flank; 56 terminals; 0.5 mm pitch, 8 mm x 8 mm x 0.85 mm body

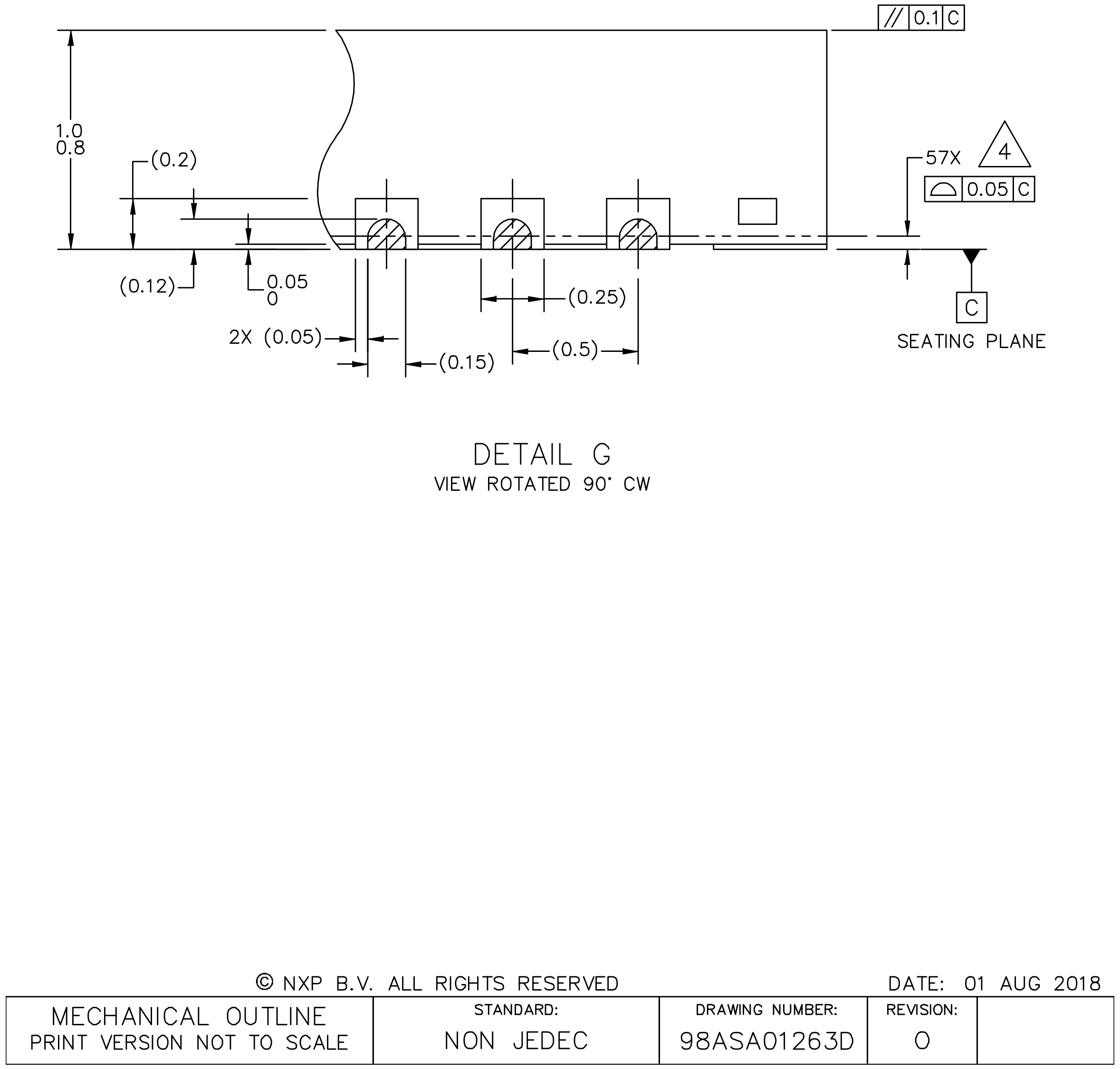


Figure 2. Package outline detail of HVQFN56 (SOT684-25(DD))

NOTES:

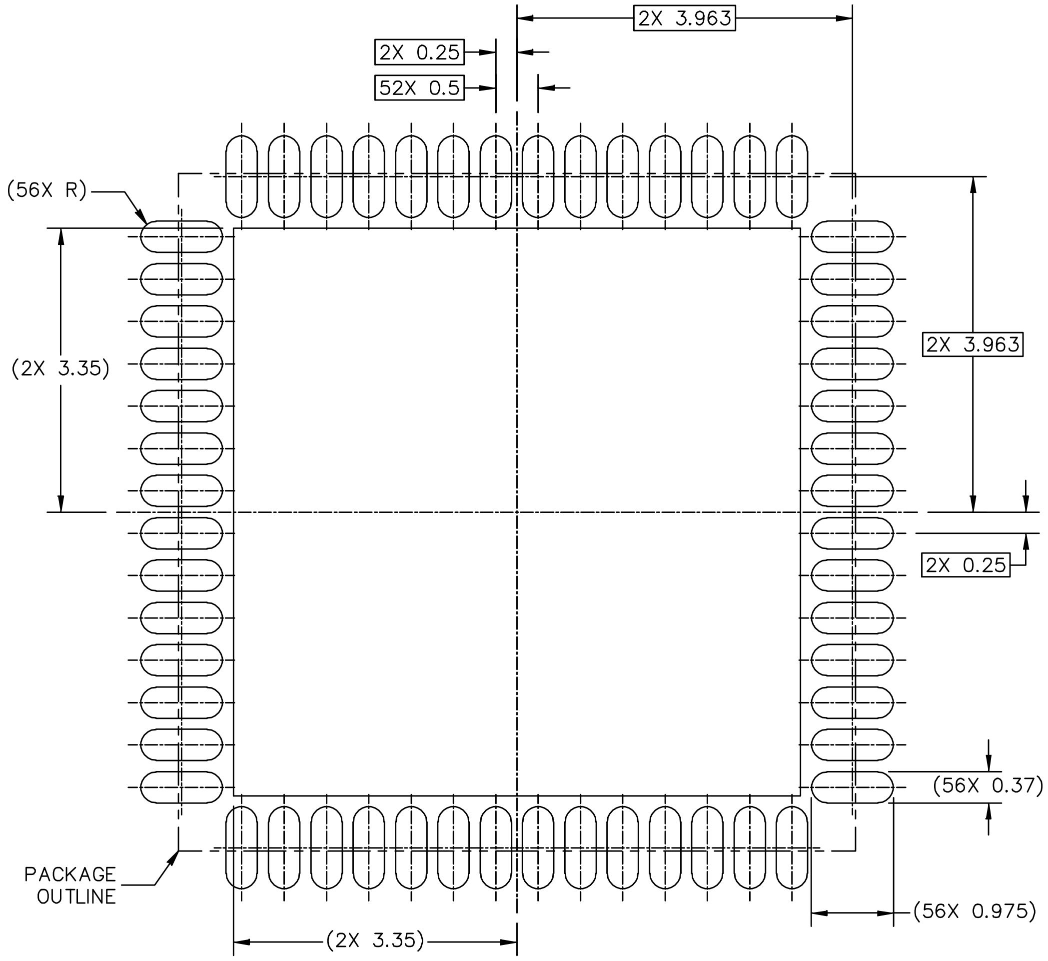
1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M−1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.25 MM.

DATE: 01 AUG 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01263D	REVISION: 0	

Figure 3. Package outline note HVQFN56 (SOT684-25(DD))

3 Soldering



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

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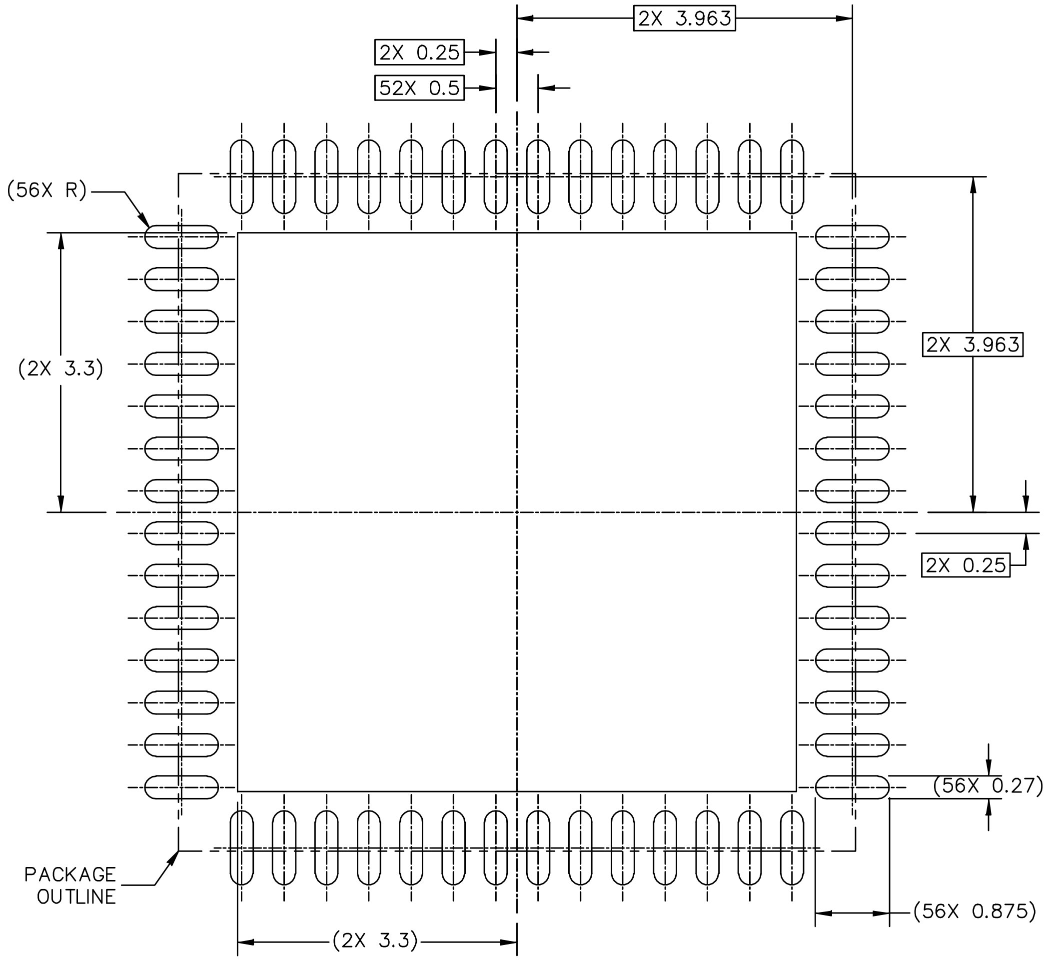
Figure 4. Reflow soldering footprint part1 for HVQFN56 (SOT684-25(DD))



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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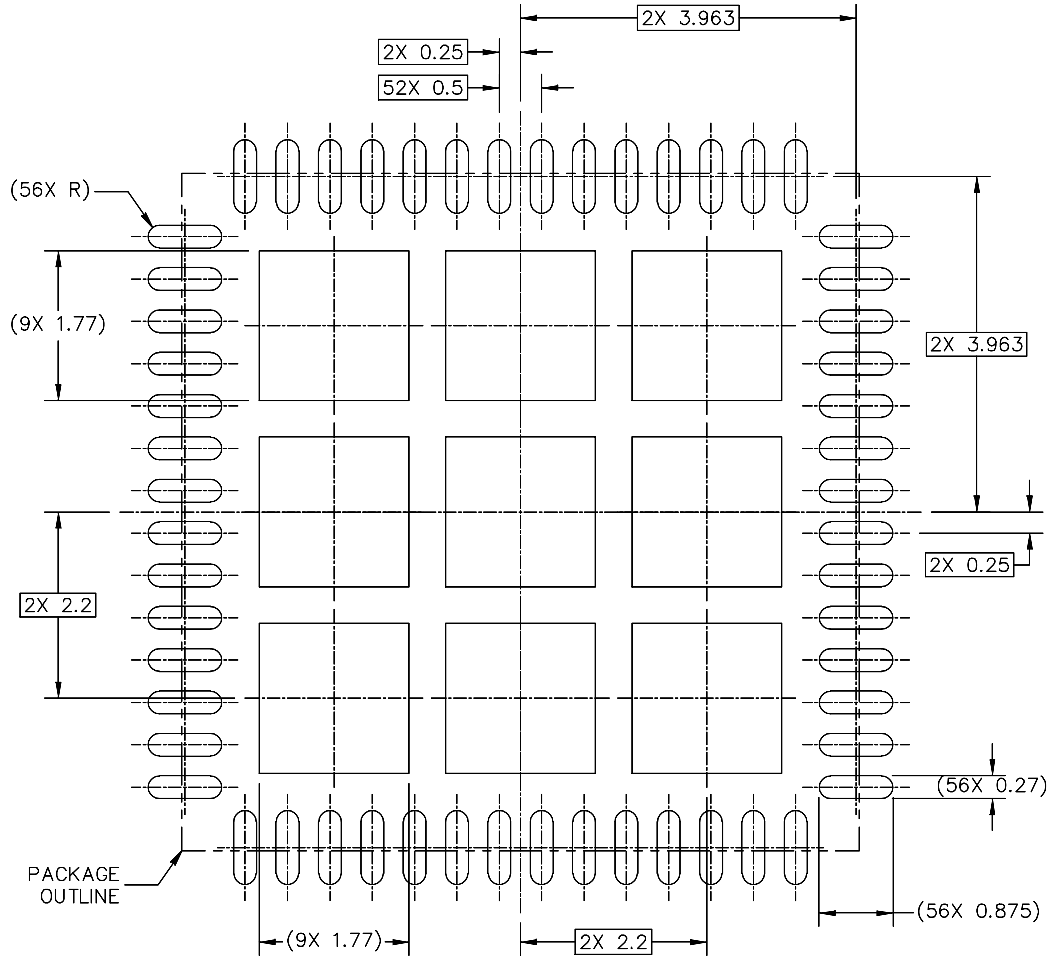
DATE: 01 AUG 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01263D	REVISION: 0	

Figure 5. Reflow soldering footprint part2 for HVQFN56 (SOT684-25(DD))



RECOMMENDED STENCIL THICKNESS 0.125 OR 0.15

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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DATE: 01 AUG 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01263D	REVISION: O	

Figure 6. Reflow soldering footprint part3 for HVQFN56 (SOT684-25(DD))

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